# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS122A - DECEMBER 1983 - REVISED JANUARY 1995

- Bidirectional Bus Transceivers in High-Density 20-Pin Packages
- Inverting Logic
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

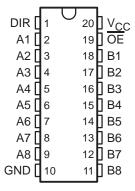
#### description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending upon the level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.

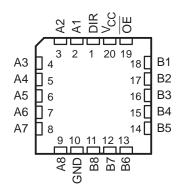
The -1 version of the SN74ALS640B is identical to the standard version, except that the recommended maximum  $I_{OL}$  for the -1 version is increased to 48 mA. There is no -1 version of the SN54ALS640B.

The SN54ALS640B and SN54AS640 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS640B and SN74AS640 are characterized for operation from 0°C to 70°C.

SN54ALS640B, SN54AS640 . . . J PACKAGE SN74ALS640B, SN74AS640 . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS640B, SN54AS640 . . . FK PACKAGE (TOP VIEW)

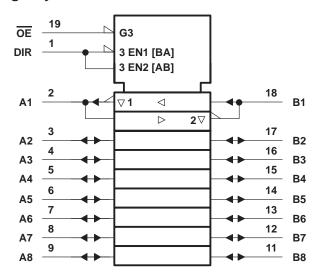


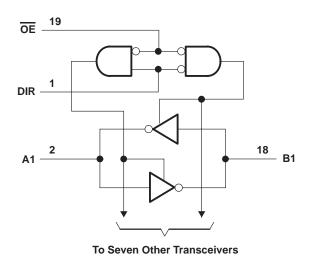
#### **FUNCTION TABLE**

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

#### logic symbol†

#### logic diagram (positive logic)





<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	
Input voltage, V <sub>I</sub> : All inputs	
I/O ports	5.5 V
Operating free-air temperature range, TA: SN54	\LS640B55°C to 125°C
SN74	ALS640B 0°C to 70°C
Storage temperature range	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN	4ALS64	0B	SN7	4ALS64	0B	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-12			-15	mA
la.	Low lovel output ourrent			12			24	mA
IOL	Low-level output current						48§	IIIA
TA	Operating free-air temperature	-55		125	0		70	°C

<sup>§</sup> Applies only to the -1 version and only if V<sub>CC</sub> is between 4.75 V and 5.25 V



# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 **OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS**

SDAS122A - DECEMBER 1983 - REVISED JANUARY 1995

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CON	IDITIONS	SNS	4ALS64	0B	SN7	4ALS64	0B	UNIT	
	PARAMETER	1EST CON	DITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP	MAX	UNII	
٧ıK		V <sub>CC</sub> = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2	2		V <sub>CC</sub> -2	2			
\/~			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V	
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V	
			$I_{OH} = -15 \text{ mA}$				2				
V <sub>OL</sub>			I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4		
		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA					0.35	0.5	V	
			$I_{OL} = 48 \text{ mA}^{\ddagger}$					0.35	0.5		
Ī	Control inputs	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 7 V			0.1			0.1	mA	
Ч	A or B ports	vCC = 5.5 v	V <sub>I</sub> = 5.5 V	0.1					0.1	III/A	
	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20		
ΙΗ	A or B ports§	VCC = 5.5 V,	V   = 2.7 V			20			20	μΑ	
I	Control inputs	\\\ 0.0 - 5.5 \\	V <sub>I</sub> = 0.4 V			-0.1			-0.1	mA	
II∟	A or B ports§	V <sub>CC</sub> = 5.5 V,	V  = 0.4 V	-0.1		-0.1			-0.1	IIIA	
IOI		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA	
			Outputs high		19	50		19	45		
ICC		V <sub>CC</sub> = 5.5 V	Outputs low		27	60		27	55	mA	
			Outputs disabled		28	55		28	50		

# switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> R1 R2	_ = 50 pF l = 500	2,	,	UNIT
			SN54AL	S640B	SN74AL		
			MIN	MAX	MIN	MAX	
tPLH	A or B	D A	2	14	2	11	ns
t <sub>PHL</sub>	AOID	B or A	2	13	2	10	
<sup>t</sup> PZH	ŌĒ	A D	4	25	4	21	ns
t <sub>PZL</sub>	OE	A or B	5	27	5	24	115
<sup>t</sup> PHZ	ŌĒ	A or B	2	12	2	10	ne
t <sub>PLZ</sub>	OE .	AUIB	3	20	3	15	ns

<sup>#</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C. ‡ Applies only to the -1 version and only if  $V_{CC}$  is between 4.75 V and 5.25 V § For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

SDAS122A - DECEMBER 1983 - REVISED JANUARY 1995

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub> : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, T <sub>A</sub> : SN54AS640	−55°C to 125°C
SN74AS640	0°C to 70°C
Storage temperature range	_65°C to 150°C

#### recommended operating conditions

		SI	N54AS64	0	SI	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-12			-15	mA
lOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST CO	NOITIONS	SI	N54AS64	40	SN	174AS64	10	LINUT	
	PARAMETER	1551 CO	NDITIONS	MIN	TYP‡	MAX	MIN	TYP <sup>‡</sup>	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V	
	*	V <sub>CC</sub> = 4.5 V,	$I_{OH} = -2 \text{ mA}$	Vcc -2	2						
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	I <sub>OH</sub> = −2 mA				V <sub>CC</sub> -2	)			
Vон			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V	
		V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.4							
			$I_{OH} = -15 \text{ mA}$				2.4				
V		V 45V	I <sub>OL</sub> = 48 mA		0.3	0.55				V	
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA					0.35	0.55		
1.	Control inputs	V 55V	V <sub>I</sub> = 7 V			0.1			0.1	A	
'1	A or B ports	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 5.5 V			0.1			0.1	mA	
	Control inputs	V 55V				20			20	^	
ΉΗ	A or B ports§	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			70			70	μΑ	
1	Control inputs	V 55V	V- 0.4.V			-0.5			-0.5	A	
IIL	A or B ports§	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.4 V	-0.75		-		-0.75	mA		
Io¶	•	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-50		-150	-50		-150	mA	
Icc			Outputs high		37	58		37	58		
		V <sub>CC</sub> = 5.5 V	Outputs low		78	123		78	123	mA	
			Outputs disabled		51	80		51	80		

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

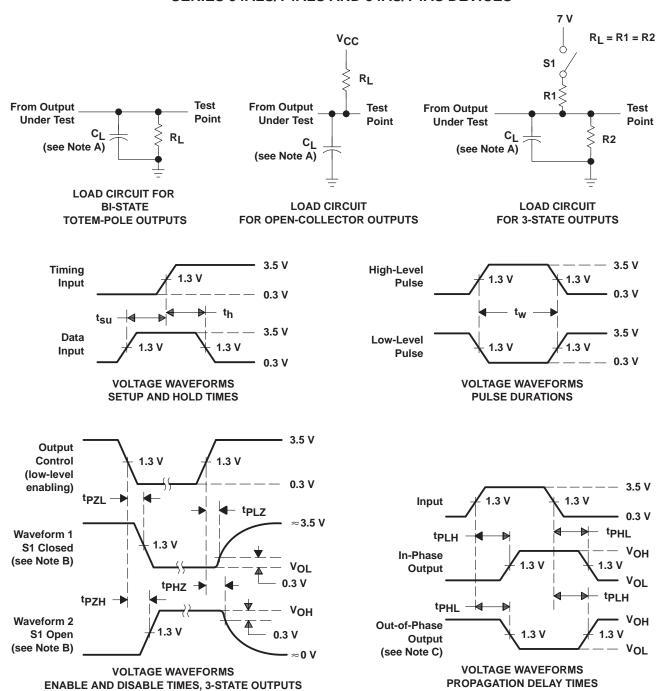
# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SDAS122A - DECEMBER 1983 - REVISED JANUARY 1995

# switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> R1 R2	= 50 pF = 500 \(  \)	2,		UNIT
			SN54A	S640	SN74A		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	D A	1	8	2	7	ns
t <sub>PHL</sub>	AOID	B or A	1	7	2	6	115
<sup>t</sup> PZH	ŌĒ	A a. D	2	10	2	8	ns
tPZL	OE .	A or B	2	12	2	10	115
<sup>t</sup> PHZ	ŌĒ	A or B	2	9	2	8	ns
<sup>t</sup> PLZ	OL	AOIB	2	16	2	13	118

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
  - All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_{\Gamma} = t_{f} = 2$  ns, duty cycle = 50%.
  - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







24-Aug-2018

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-8872701RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8872701RA SNJ54ALS640BJ	Samples
5962-8955301RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8955301RA SNJ54AS640J	Samples
SN54ALS640BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS640BJ	Samples
SN74ALS640B-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B-1	Samples
SN74ALS640B-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B-1	Samples
SN74ALS640B-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS640B-1N	Samples
SN74ALS640B-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B-1	Samples
SN74ALS640BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B	Samples
SN74ALS640BDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B	Samples
SN74ALS640BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B	Samples
SN74ALS640BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B	Samples
SN74ALS640BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS640BN	Samples
SN74ALS640BNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B	Samples
SN74ALS640BNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS640B	Samples
SN74AS640N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS640N	Samples
SN74AS640NSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS640	Samples
SNJ54ALS640BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8872701RA SNJ54ALS640BJ	Samples



#### PACKAGE OPTION ADDENDUM

24-Aug-2018

Orderable Device	Status	Package Type	_	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54AS640J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8955301RA SNJ54AS640J	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640:

Catalog: SN74ALS640B, SN74AS640





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• Military: SN54ALS640B, SN54AS640

NOTE: Qualified Version Definitions:

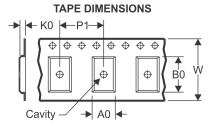
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

**PACKAGE MATERIALS INFORMATION** 

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#### TAPE AND REEL INFORMATION





A0	<u> </u>
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS640B-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS640B-1NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ALS640BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS640BNSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AS640NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

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\*All dimensions are nominal

All difficultions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS640B-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS640B-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS640BDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS640BNSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS640NSR	SO	NS	20	2000	367.0	367.0	45.0

#### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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